

SOT1308-1

Plastic thermal enhanced very thin small outline package; no leads; 16 terminals

10 June 2016

Package information

1. Package summary

Terminal position code	D (double)
Package type descriptive code	HVSON16
Package type industry code	HVSON16
Package style descriptive code	HVSON (thermal enhanced very thin small outline; no leads)
Package body material type	P (plastic)
IEC package outline code	---
JEDEC package outline code	MO-229
JEITA package outline code	---
Mounting method type	S (surface mount)
Issue date	4-7-2011

Table 1. Package summary

Symbol	Parameter		Min	Typ	Nom	Max	Unit
D	package length		5.4	-	5.5	5.6	mm
E	package width		3.4	-	3.5	3.6	mm
A	seated height		0.8	-	0.85	1	mm
e	nominal pitch		-	-	0.65	-	mm
n ₂	actual quantity of termination		-	-	16	-	



2. Package outline

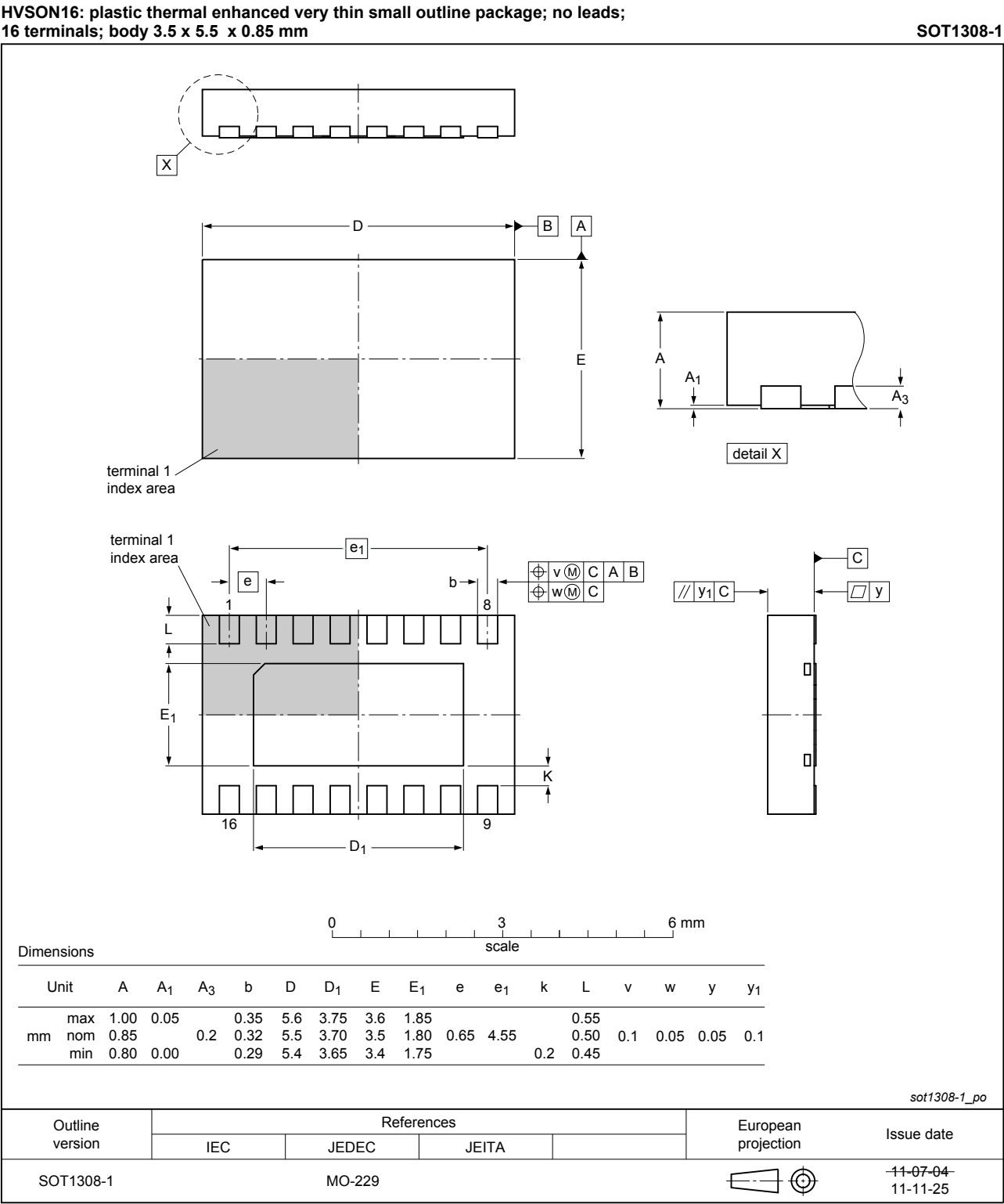


Fig. 1. Package outline HVSON16 (SOT1308-1)

3. Soldering

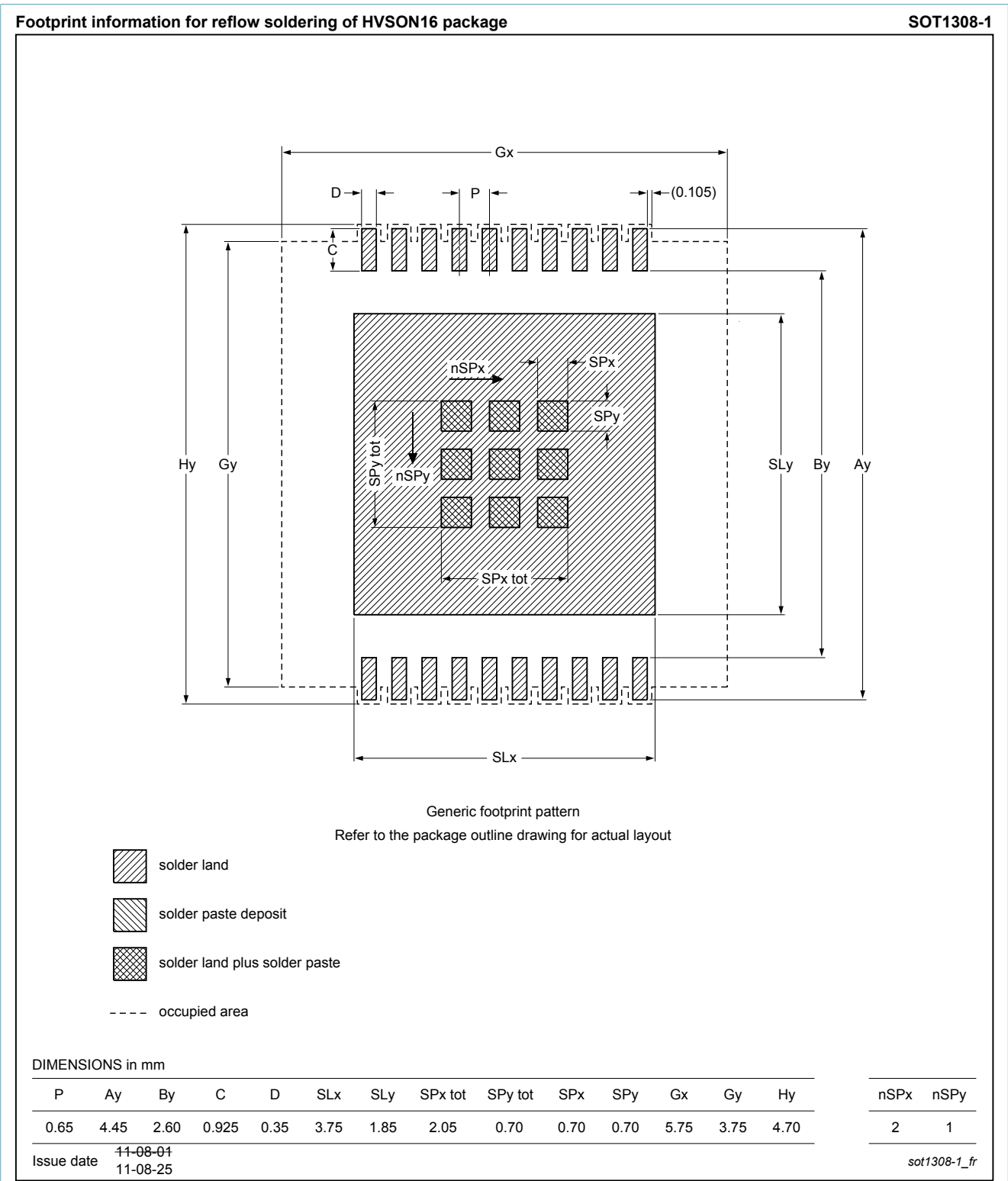


Fig. 2. Reflow soldering footprint for HVSON16 (SOT1308-1)

4. Legal information

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